Silicon P Channel MOS FET Low FrequencyPower Switching

HITACHI

ADE-208-512 A 2nd. Edition

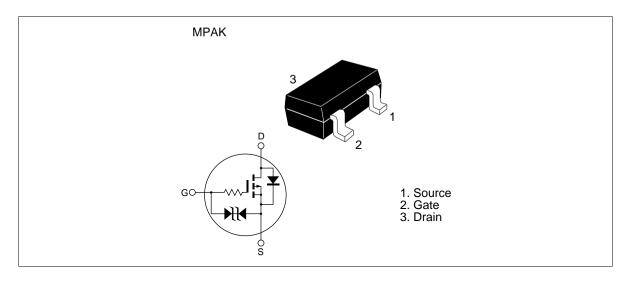
Features

Low on-resistance

 $R_{DS(on)} = 0.5 \ \Omega$ typ. (at $V_{GS} = -4V$, $I_D = -100 \ mA$)

- 2.5V gate drive devices.
- Small package (MPAK).

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-30	V	
Gate to source voltage	V _{GSS}	±10	V	
Drain current	I _D	-0.3	А	
Drain peak current	I _{D(pulse)} * ¹	-0.6	А	
Channel dissipation	Pch	150	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. PW \leq 10µs, duty cycle \leq 1 %

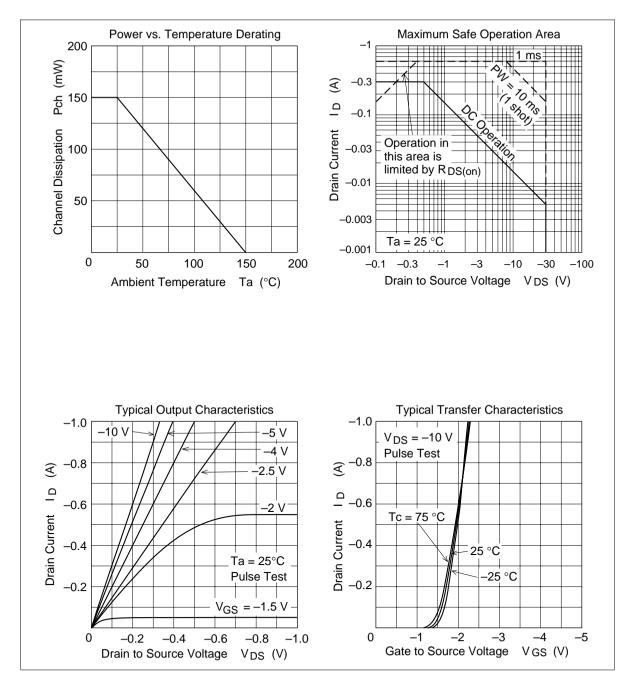
Electrical Characteristics ($Ta = 25^{\circ}C$)

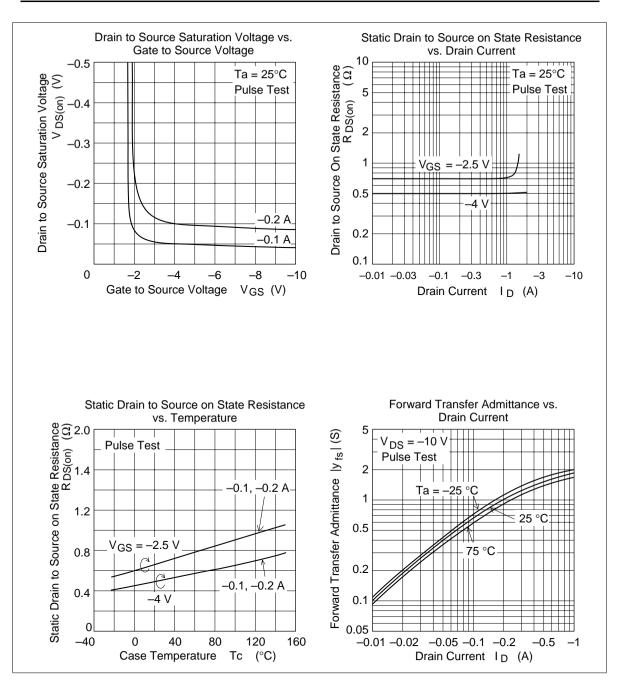
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	-30	_	—	V	$I_{\rm D} = -10 \mu A, V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10	—	—	V	$I_{\rm G} = \pm 100 \mu A, V_{\rm DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	—	-1.0	μA	$V_{\rm DS} = -30$ V, $V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	—	_	±5.0	μA	$V_{GS} = \pm 6.5 V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5	_	-1.5	V	$I_{\rm D} = -10\mu A, V_{\rm DS} = -5V$
Static drain to source on state		—	0.5	0.65	Ω	$I_{\rm D} = -100 {\rm mA}$
resistance						$V_{GS} = -4V^{*1}$
	$R_{\text{DS(on)}}$	—	0.7	1.2	Ω	$I_{D} = -40 \text{mA}$
						$V_{GS} = -2.5 V^{*1}$
Forward transfer admittance	y _{fs}	0.4	0.65	_	S	$I_{D} = -100 \text{mA}$
						$V_{DS} = -10V^{*1}$
Input capacitance	Ciss	—	45	—	pF	$V_{DS} = -10V$
Output capacitance	Coss	—	76	—	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	5.4	—	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	120	_	ns	$V_{GS} = -4V$
Rise time	t,	_	340	_	ns	I _D = -150mA
Turn-off delay time	t _{d(off)}	_	850	_	ns	$R_{L} = 66.6\Omega$
Fall time	t _f	_	550	—	ns	

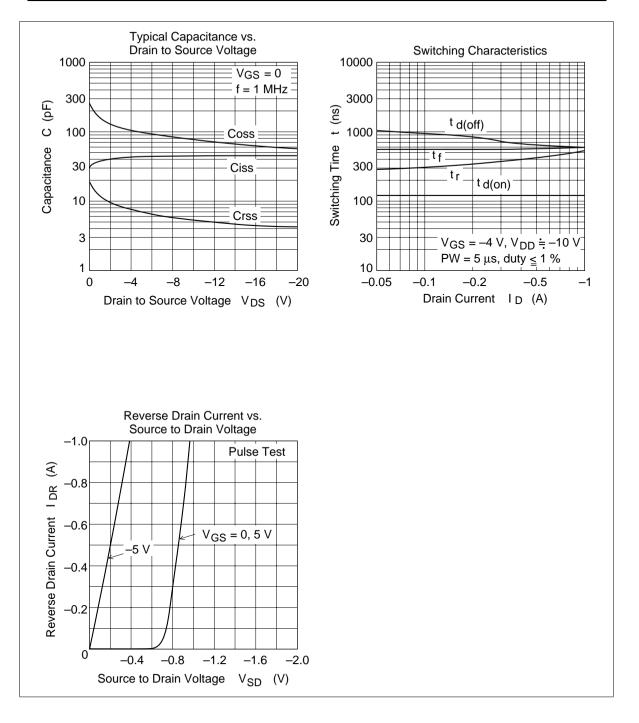
Notes: 1. Pulse test

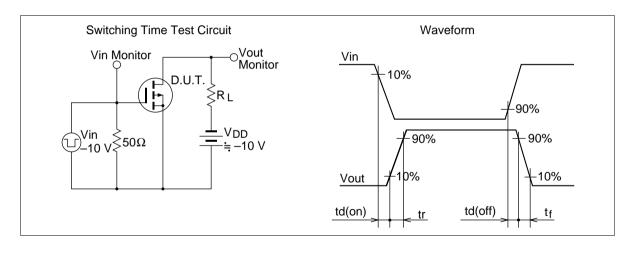
2. Marking is "ZU-".

Main Characteristics









Unit: mm

Package Dimensions

 $0.65_{-0.3}^{+0.1}$ $0.4 \stackrel{+ 0.10}{- 0.05}$ $0.16^{+0.10}_{-0.06}$ $2.8 ^{+0.2}_{-0.6}$ 0 ~ 0.1 1.5 + $0.65 + 0.1 \\ - 0.3$ 0.95 0.95 1.9 $2.8^{+0.3}_{-0.1}$ 0.3 $1.1^{+0.2}_{-0.1}$ Hitachi Code MPAK EIAJ SC–59A TO–236Mod JEDEC

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